

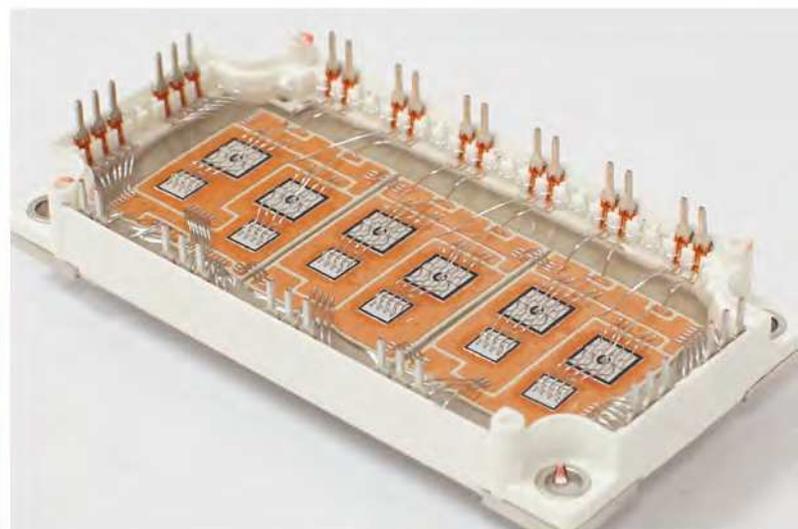
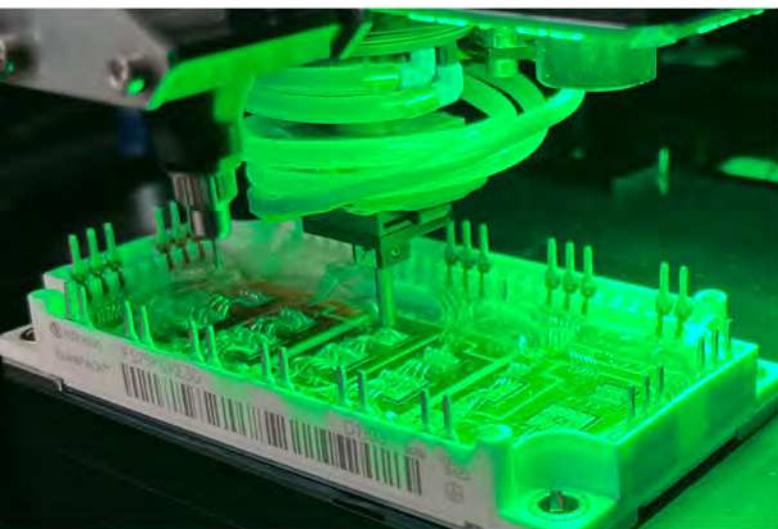


SINTER BONDER

FOR POWER MODULES



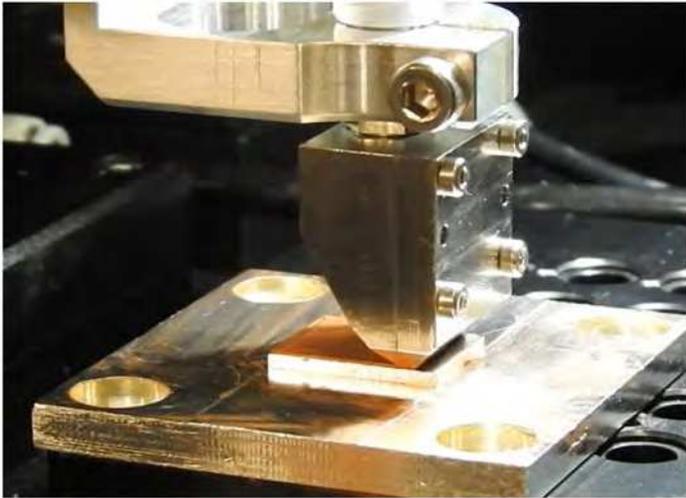
- Chip to Substrate bonding (e.g. Si IGBTs, SiC MOSFET)
- Substrate to baseplate bonding (e.g. DBC or AMB to copper baseplate)
- Power Module to heat sink bonding (e.g. T-Pak, IPMs)
- DIE-Transfer Process (DTF)
- Sintering Preforms
- Dry Sintering Process Capability (Hot-Tacking)
- Cold Tacking: Tacking-Agent Dispensing or Jetting
- Wet-Sintering Process Capability (Slit-Nozzle Dispensing)
- Hot Pick & Place (Pick-up Tool temp. up to 400°C, Substrate temp. up to 450°C)
- Solder Preform Cutter and Feeder
- High Force Bonding (up to 35 kg)
- Inline compatible with most Vacuum Soldering / Sintering Press equipment



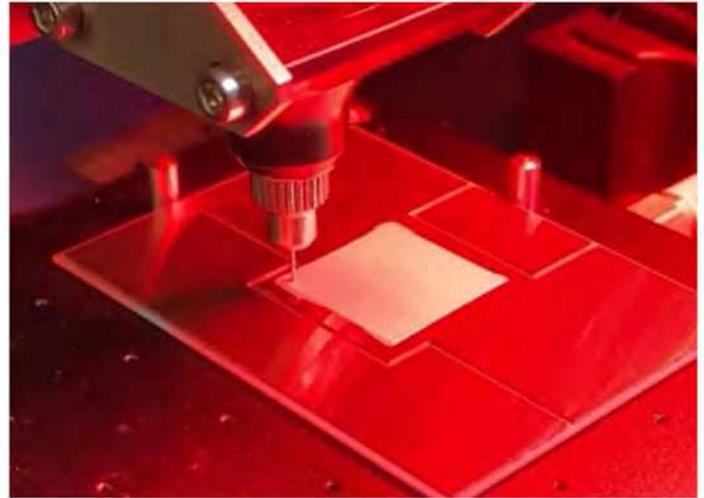
Power Module Bonding

For more information

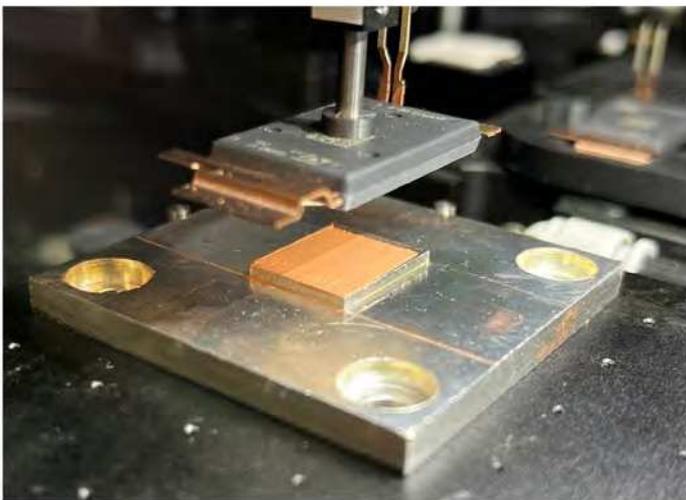




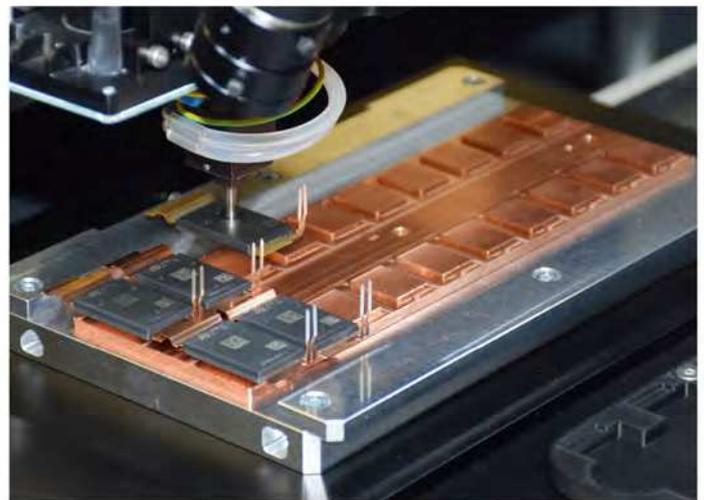
Dispensing of the Ag- or Cu-Sinter Paste with Tresky's Slit-Nozzle



Optionally, a tacking-agent can be applied to the sinter paste for positioning and fixation of the chip



Bonding of a T-Pak by means of Cu-Sinter Paste



Bonded T-Paks on the substrate

For more information about our products or services please visit our website.

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